### 3.4mm RIGHT ANGLE LED INDICATOR

Part Number: L-1384AD/1GD Green

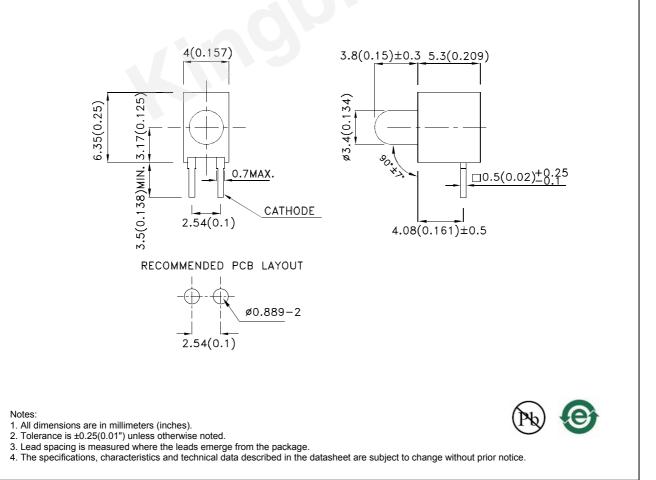
#### Features

- Ideal for card edge status indication.
- Wide viewing angle.
- High reliability-life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

#### **Package Dimensions**



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#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-1384AD/1GD	Green (GaP)	Green Diffused	10	20	60°

Notes:

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Green	2.2	2.5	V	I⊧=20mA
lr	Reverse Current	Green		10	uA	VR = 5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

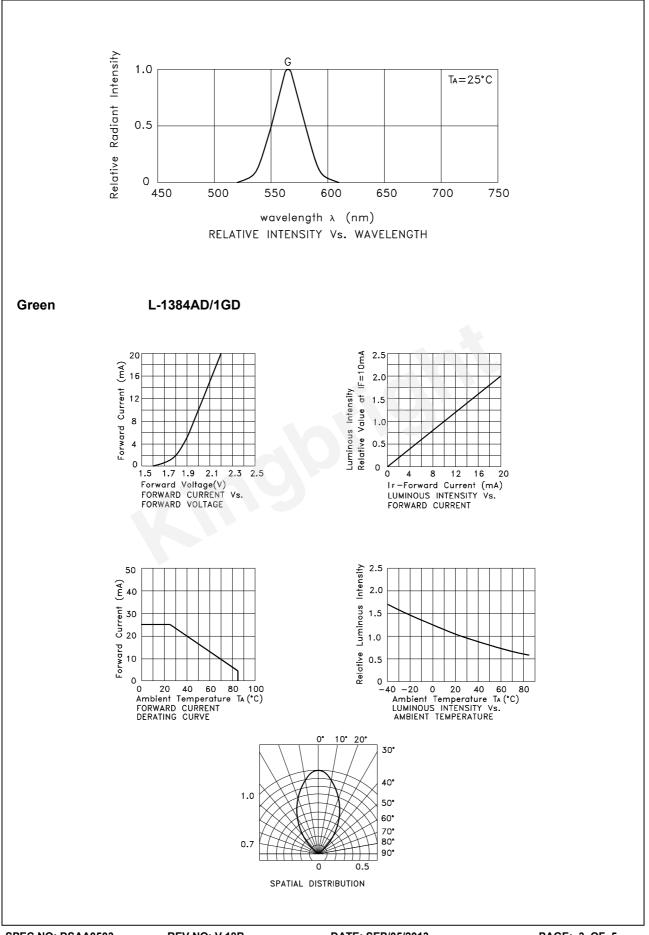
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

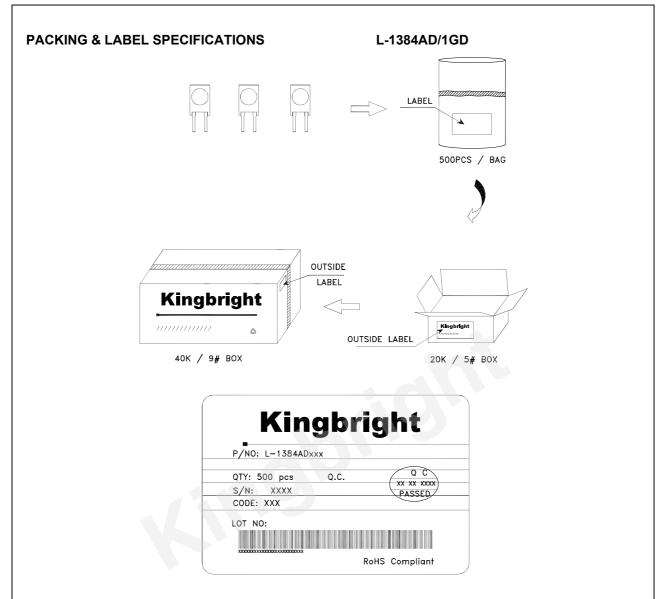
#### Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units		
Power dissipation	62.5	mW		
DC Forward Current	25	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.
 3. 5mm below package base.





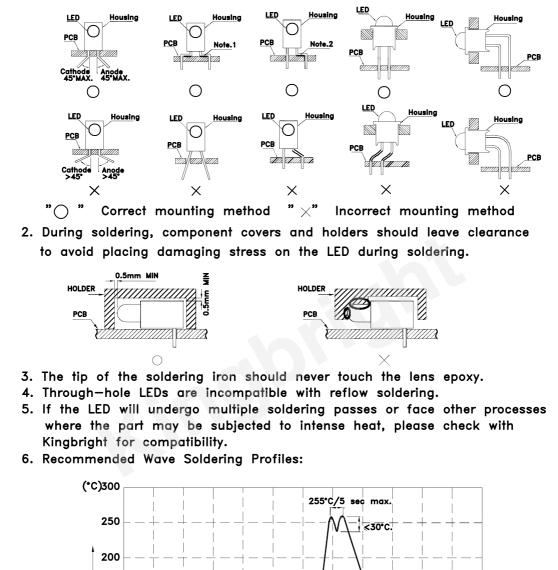
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### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



Notes:

Temperature

150

100

50

0

(85°C

Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

Time(sec)

(100°C

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4°C/s<sup>|</sup>ma>

Preheat time: 60

4.Fixtures should not incur stress on the component when mounting and during soldering process.
5.SAC 305 solder alloy is recommended.
6.No more than one wave soldering pass.